

Supplier Name: Texas Instruments Inc. (DUNSH 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 05/28/2022

Details for "CD74HCT154M96G4"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
CD74HCT154M96G4	NIPDAU	Level-1-260C-UNLIM	TI TAIWAN A/T	DW 24	7.52x15.36x2.35	955.9

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Iron	7439-89-6	0.000001	0.000321	3	0	0
Other Nonferrous Metals and Alloys	Calcium	7440-70-2	0.000001	0.000321	3	0	0
Other Nonferrous Metals and Alloys	Yttrium	7440-65-5	0.000002	0.000643	6	0	0
Precious Metals	Gold	7440-57-5	0.311276	99.997751	999978	0.032563	326
Precious Metals	Silver	7440-22-4	0.000003	0.000964	10	0	0
Sub-Total			0.311283	100	1000000	0.032564	326
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.590723	79.999973	800000	0.061796	618
Thermoplastics	Epoxy	85954-11-6	0.147681	20.000027	200000	0.015449	154
Sub-Total			0.738404	100	1000000	0.077245	772
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	432.933159	97.05	970500	45.289574	452896
Copper and Its Alloys	Iron	7439-89-6	11.598415	2.6	26000	1.213322	12133
Copper and Its Alloys	Phosphorus	7723-14-0	0.669139	0.15	1500	0.069999	700
Zinc and Its Alloys	Zinc	7440-66-6	0.892186	0.2	2000	0.093332	933
Sub-Total			446.092899	100	1000000	46.666228	466662
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	1.475311	95.119987	951200	0.154334	1543
Precious Metals	Gold	7440-57-5	0.012098	0.780013	7800	0.001266	13
Precious Metals	Palladium	7440-05-3	0.063591	4.1	41000	0.006652	67
Sub-Total			1.551	100	1000000	0.162252	1623
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	444.234615	88	880000	46.471831	464718
Other Plastics and Rubber	Carbon Black	1333-86-4	1.514436	0.3	3000	0.158427	1584
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	2.776466	0.55	5500	0.290449	2904
Thermoplastics	Epoxy	85954-11-6	56.286545	11.15	111500	5.888192	58882
Sub-Total			504.812062	100	1000000	52.808899	528089
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	2.416691	100	1000000	0.252812	2528
Sub-Total			2.416691	100	1000000	0.252812	2528
Total			955.922339			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSi or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
 For further environmental statements, please go to www.ti.com/ecoinfo
 Created on: 05/28/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.